
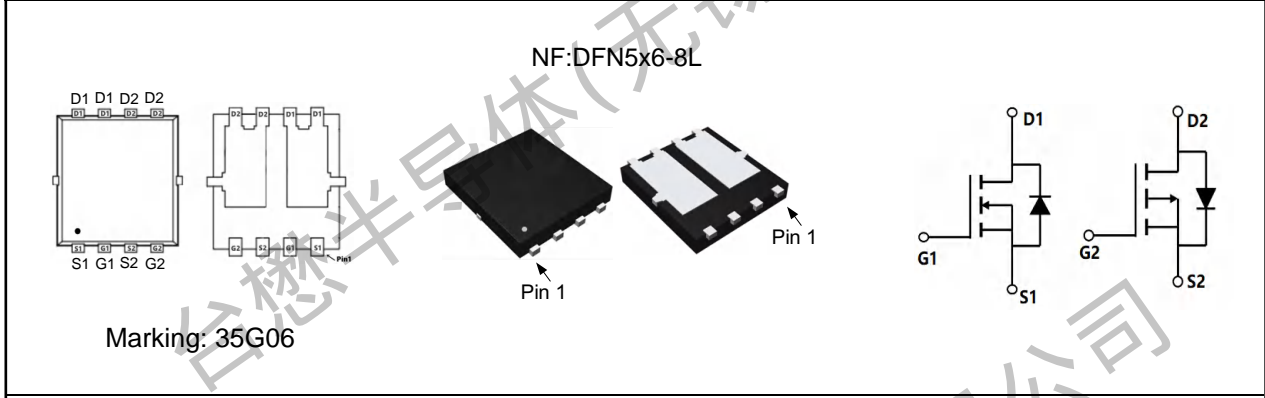


TM35G06NF

N+P -Channel Enhancement Mode Mosfet

<p>General Description</p> <ul style="list-style-type: none"> • Low $R_{DS(ON)}$ • RoHS and Halogen-Free Compliant <p>Applications</p> <ul style="list-style-type: none"> • Load switch • PWM 	<p>General Features</p> <p>N Channel $V_{DS} = 60V, I_D = 35A$ $R_{DS(ON)} = 12m\Omega @ V_{GS} = 10V$</p> <p>P Channel $V_{DS} = -60V, I_D = -34A$ $R_{DS(ON)} = 29m\Omega @ V_{GS} = -10V$</p> <p>100% UIS Tested 100% R_g Tested</p> 
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Absolute Maximum Ratings ($T_A = 25^\circ C$ Unless Otherwise Noted)

Symbol	Parameter	Rating		Units
		N-Channel	P-Channel	
V_{DS}	Drain-Source Voltage	60	-60	V
V_{GS}	Gate-Source Voltage	± 30	± 20	V
$I_D @ T_A = 25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V$	35	-34	A
$I_D @ T_A = 100^\circ C$	Continuous Drain Current, $V_{GS} @ 10V$	26	-25	A
I_{DM}	Pulsed Drain Current	180	-140	A
P_D	Total Power Dissipation	75	88	W
T_{STG}	Storage Temperature Range	-55 to 175	-55 to 175	$^\circ C$
T_J	Operating Junction Temperature Range	-55 to 175	-55 to 175	$^\circ C$

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-Ambient	---	---	$^\circ C/W$
$R_{\theta JC}$	Thermal Resistance Junction-Case	---	1.67	$^\circ C/W$



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N-CH Electrical Characteristics: ($T_C=25^{\circ}C$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
Off Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250 \mu A$	60	---	---	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{GS}=0V, V_{DS}=60V$	---	---	1	μA
I_{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0A$	---	---	± 100	nA
On Characteristics						
$V_{GS(th)}$	Gate-Source Threshold Voltage	$V_{GS}=V_{DS}, I_D=250 \mu A$	1	2	3	V
$R_{DS(on)}$	Drain-Source On Resistance	$V_{GS}=10V, I_D=30A$	---	12	15	$m \Omega$
		$V_{GS}=4.5V, I_D=20A$	---	18	23	$m \Omega$
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{DS}=25V, V_{GS}=0V, f=1MHz$	---	1928	---	pF
C_{oss}	Output Capacitance		---	136	--	
C_{rss}	Reverse Transfer Capacitance		---	120	---	
Switching Characteristics						
$t_{d(on)}$	Turn-On Delay Time	$V_{DS}=30V, I_D=30A,$ $R_{ENG}=1.8 \Omega, V_{GS}=10V$	---	10	---	ns
t_r	Rise Time		---	82	---	ns
$t_{d(off)}$	Turn-Off Delay Time		---	31	---	ns
t_f	Fall Time		---	101	---	ns
Q_g	Total Gate Charge		$V_{GS}=10V, V_{DS}=30V,$	---	47	---
Q_{gs}	Gate-Source Charge	$I_D=30A$	---	8.4	---	nc
Q_{gd}	Gate-Drain "Miller" Charge		---	11.55	---	nc
Drain-Source Diode Characteristics						
V_{SD}	Diode Forward Voltage	$V_{GS}=0V, I_{SD}=30A$	---	---	1.2	V
I_S	Continuous Drain Current	$V_D=V_G=0V$	---	---	35	A
I_{SM}	Pulsed Drain Current		---	---	140	A
T_{rr}	Reverse Recovery Time	$I_F=30A, T_J=25^{\circ}C$	---	14	---	ns
Q_{rr}	Reverse Recovery Charge	$dI/dt=100A/us$	---	20	---	nc

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Typical Characteristics: ($T_c=25^\circ\text{C}$ unless otherwise noted)

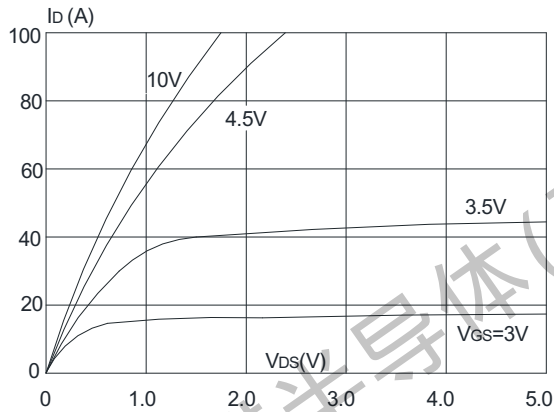


Figure 1: Output Characteristics

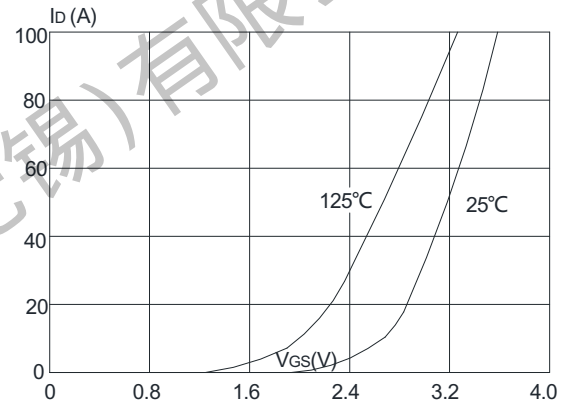


Figure 2: Typical Transfer Characteristics

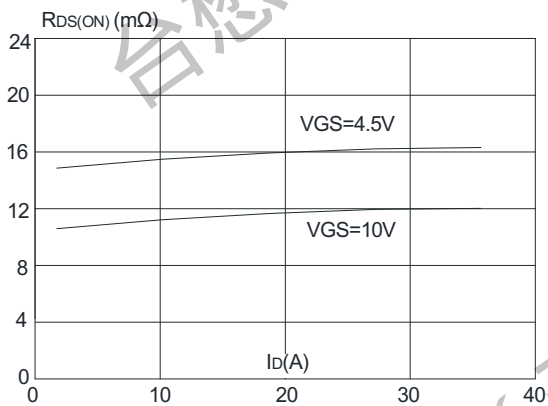


Figure 3: On-resistance vs. Drain Current

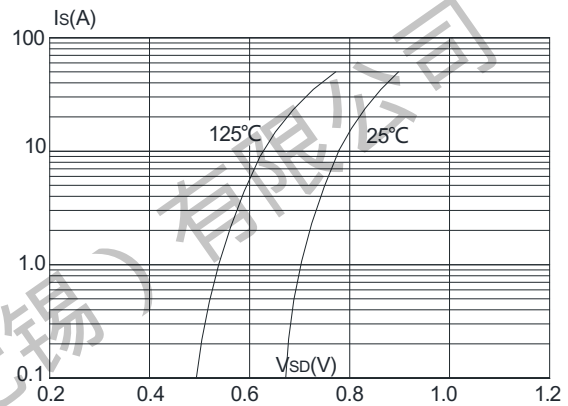


Figure 4: Body Diode Characteristics

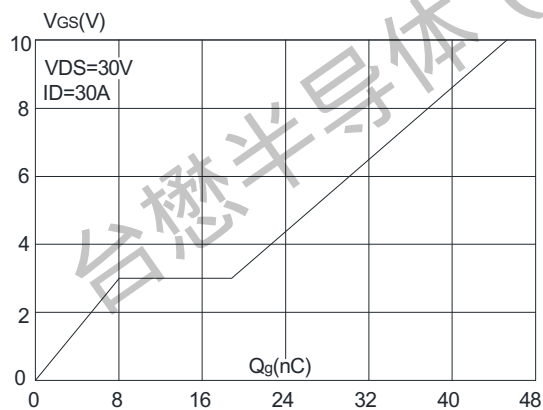


Figure 5: Gate Charge Characteristics

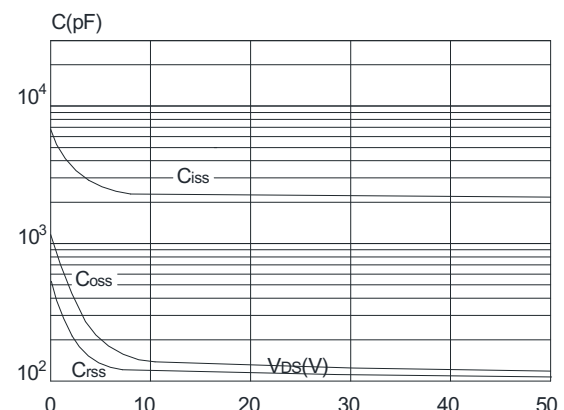


Figure 6: Capacitance Characteristics

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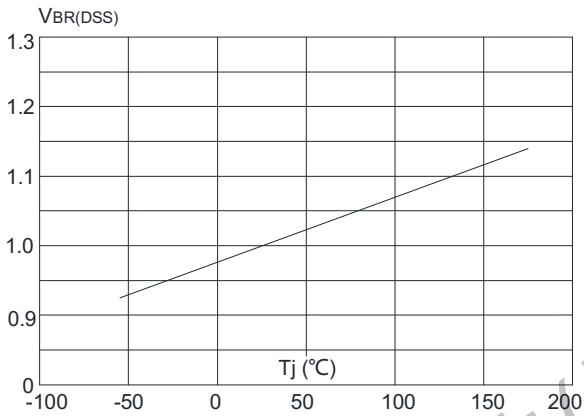


Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

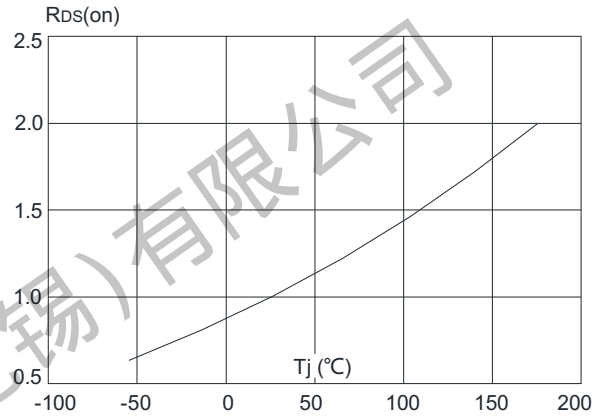


Figure 8: Normalized on Resistance vs. Junction Temperature

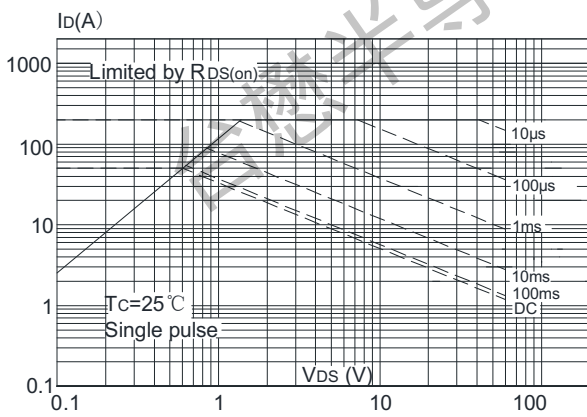


Figure 9: Maximum Safe Operating Area

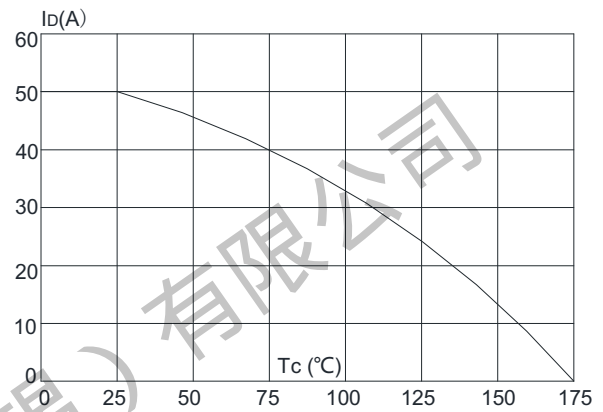


Figure 10: Maximum Continuous Drain Current vs. Case Temperature

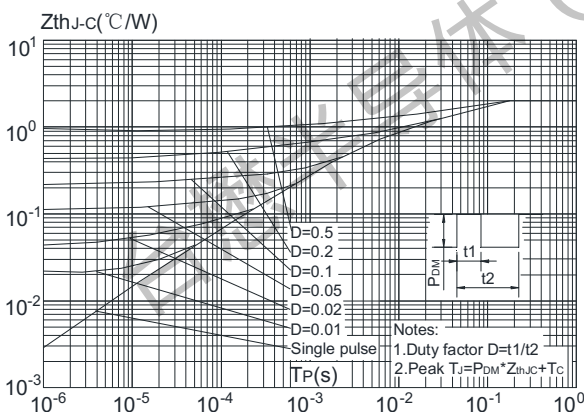


Figure.11: Maximum Effective Transient Thermal Impedance, Junction-to-Case

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P-CH Electrical Characteristics: ($T_c=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
Off Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\ \mu A$	-60	---	---	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{GS}=0V, V_{DS}=-60V$	---	---	-1	μA
I_{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0A$	---	---	± 100	nA
On Characteristics						
$V_{GS(th)}$	Gate-Source Threshold Voltage	$V_{GS}=V_{DS}, I_D=250\ \mu A$	-1	-2	-3	V
$R_{DS(on)}$	Drain-Source On Resistance	$V_{GS}=-10V, I_D=-15A$	---	29	36	m Ω
		$V_{GS}=-4.5V, I_D=-10A$	---	35	45	
G_{FS}	Forward Transconductance	$V_{DS}=-5V, I_D=-15A$	---	35	---	S
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{DS}=-25V, V_{GS}=0V, f=1MHz$	---	4025	---	pF
C_{oss}	Output Capacitance		---	133	---	
C_{rss}	Reverse Transfer Capacitance		---	97	---	
Switching Characteristics						
$t_{d(on)}$	Turn-On Delay Time	$V_{DD}=-30V$ $R_{GEN}=3\ \Omega, V_{GS}=-10V$	---	12	---	ns
t_r	Rise Time		---	9	---	ns
$t_{d(off)}$	Turn-Off Delay Time		---	63	---	ns
t_f	Fall Time		---	13	---	ns
Q_g	Total Gate Charge	$V_{GS}=-10V, V_{DS}=-30V,$ $I_D=-20A$	---	53	---	nC
Q_{gs}	Gate-Source Charge		---	10	---	nC
Q_{gd}	Gate-Drain "Miller" Charge		---	12	---	nC
Drain-Source Diode Characteristics						
V_{SD}	Source-Drain Diode Forward Voltage	$V_{GS}=0V, I_S=-15A, T_J=25^\circ\text{C}$	---	-0.88	-1.2	V
I_S	Continuous Drain Current	$V_D=V_G=0V$	---	---	-34	A
I_{SM}	Pulsed Drain Current	$V_D=V_G=0V$	---	---	-125	A
t_{rr}	Reverse Recovery Time	$I_{sd}=-20A, V_{GS}=0V$	---	26	---	ns
Q_{rr}	Reverse Recovery Charge	$.di/dt=-500A/\mu s$	---	29	---	nc

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Typical Characteristics: ($T_c=25^\circ\text{C}$ unless otherwise noted)

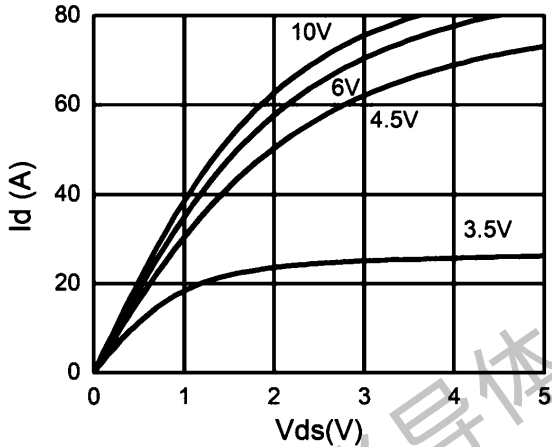


Figure 1. Output Characteristics

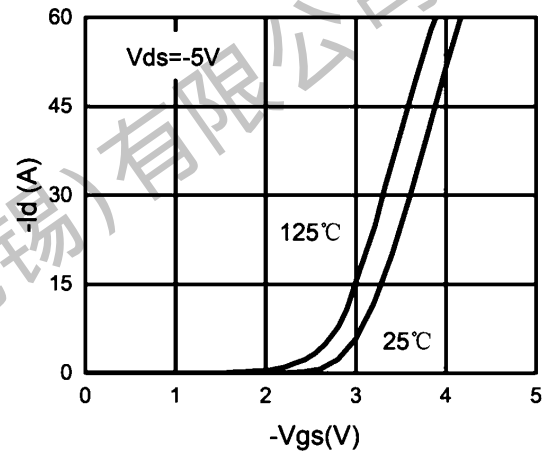


Figure 2. Transfer Characteristics

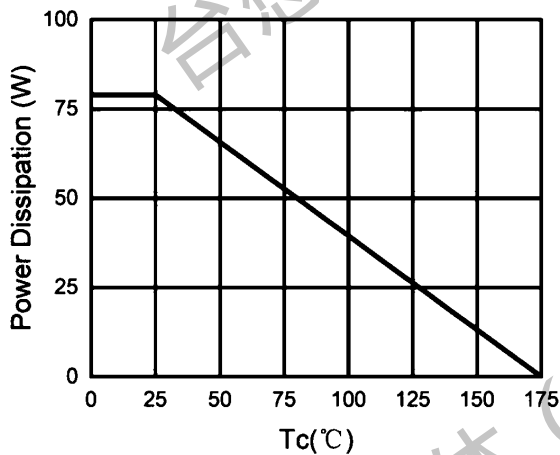


Figure 3. Power Dissipation

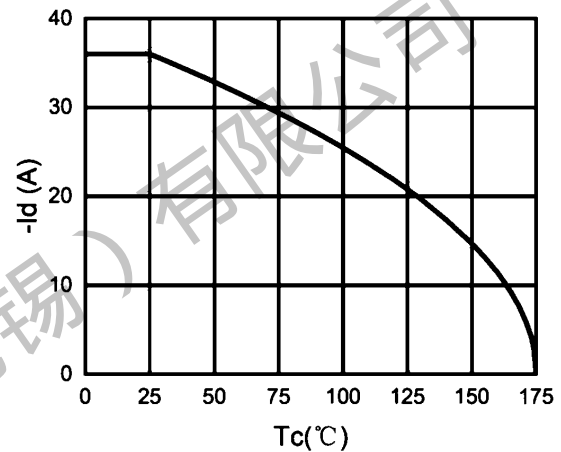


Figure 4. Drain Current

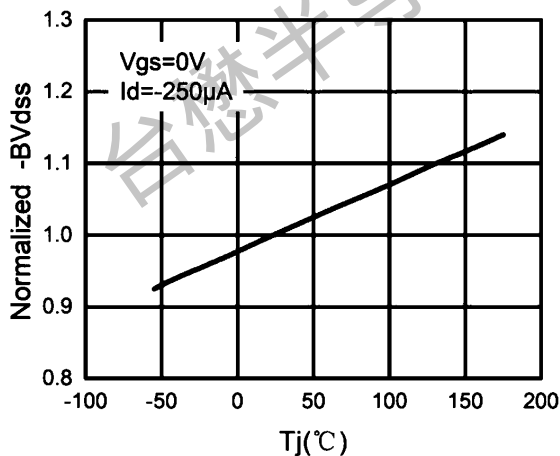


Figure 5. BV_{DSS} vs Junction Temperature

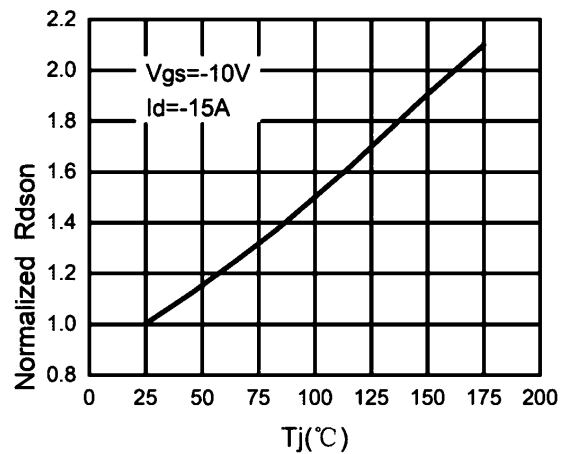


Figure 6. $R_{DS(ON)}$ vs Junction Temperature

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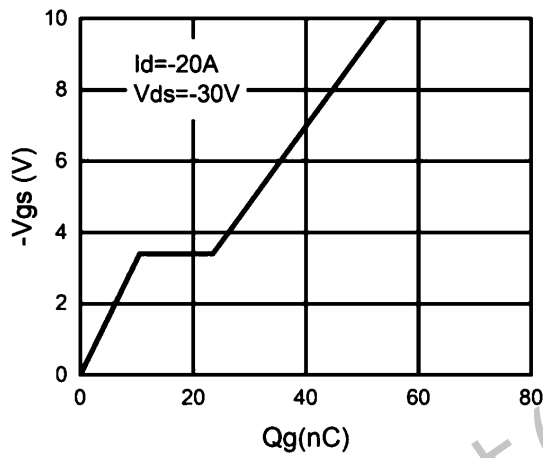


Figure 7. Gate Charge Waveforms

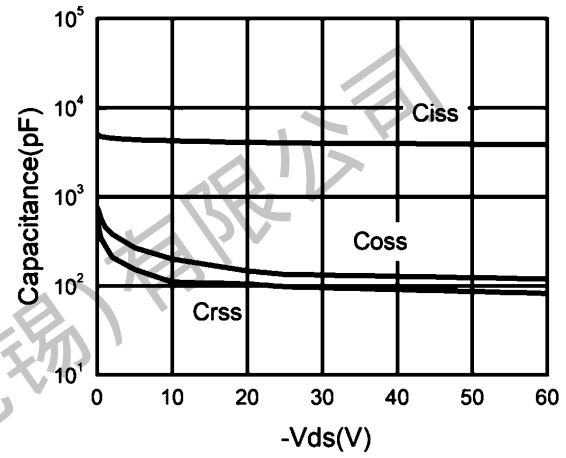


Figure 8. Capacitance

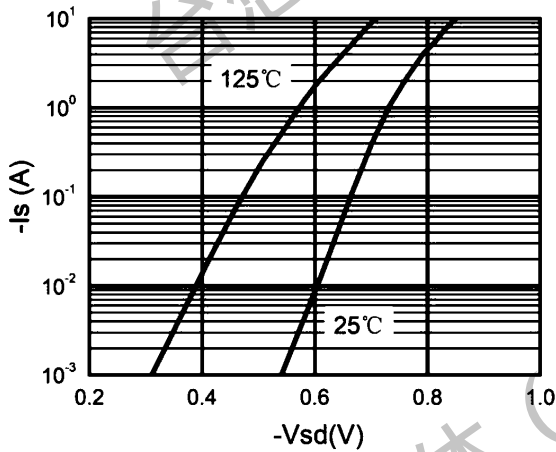


Figure 9. Body-Diode Characteristics

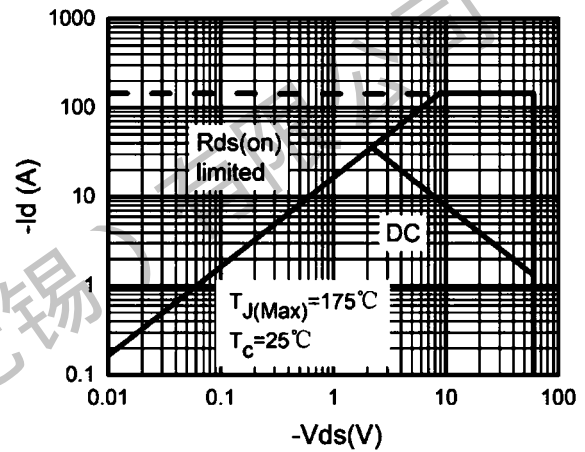
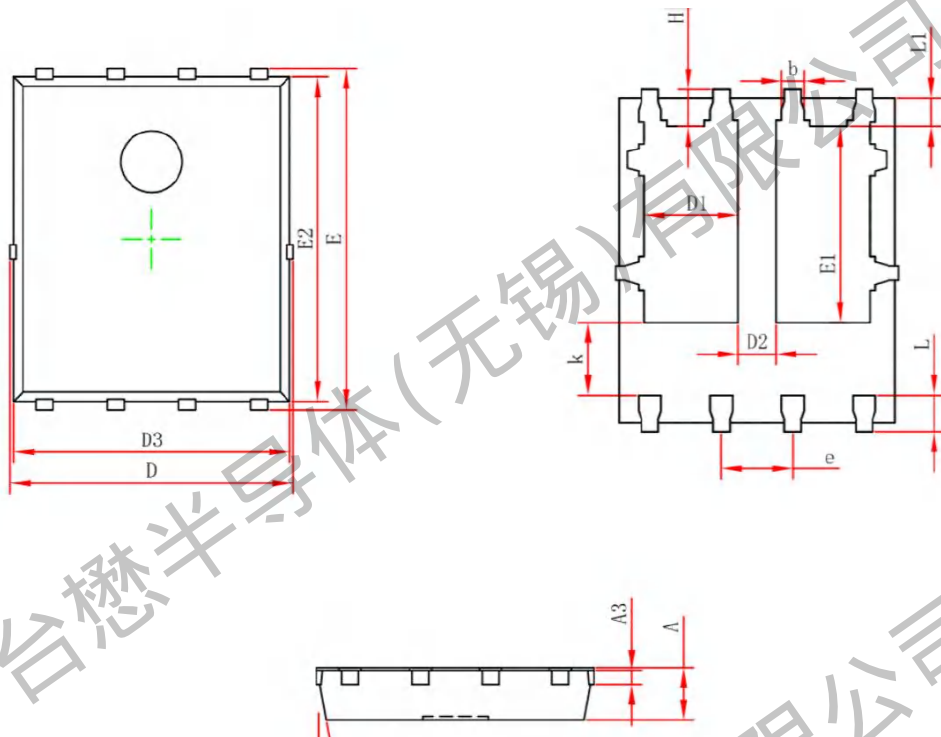


Figure 10. Maximum Safe Operating Area

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Package Mechanical Data:DFN5x6-8L

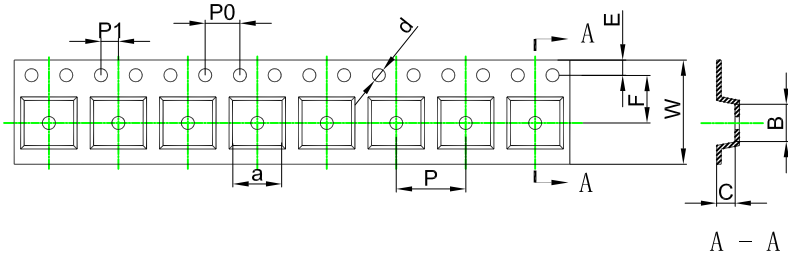


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.000	0.035	0.039
A3	0.154REF.		0.006REF.	
D	4.944	5.096	0.195	0.201
E	5.974	6.126	0.235	0.241
D1	1.470	1.870	0.058	0.074
D2	0.470	0.870	0.019	0.034
E1	3.375	3.575	0.133	0.141
D3	4.824	4.976	0.190	0.196
E2	5.674	5.826	0.223	0.229
k	1.190	1.390	0.047	0.055
b	0.350	0.450	0.014	0.018
e	1.270TYP.		0.050TYP.	
L	0.559	0.711	0.022	0.028
L1	0.424	0.576	0.017	0.023
H	0.574	0.726	0.023	0.029
θ	10°	12°	10°	12°

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PDFN5x6-8L Embossed Carrier Tape



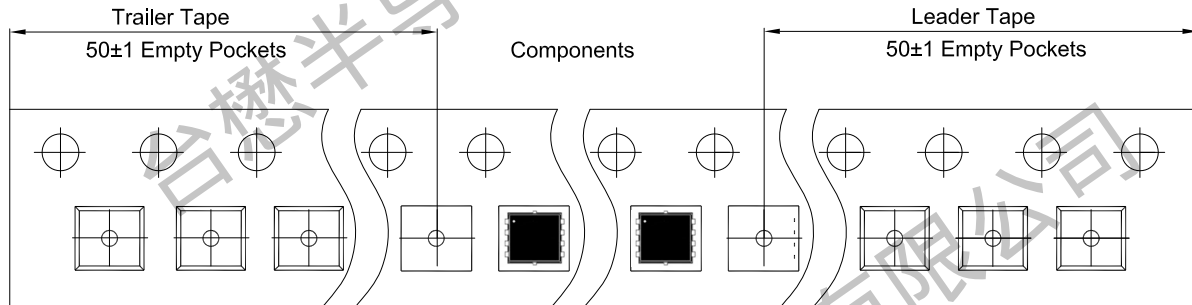
Packaging Description:

SOP-8L parts are shipped in tape. The carrier tape is made from a dissipative (carbon filled) polycarbonate resin. The cover tape is a multilayer film (Heat Activated Adhesive in nature) primarily composed of polyester film, adhesive layer, sealant, and anti-static sprayed agent. These reeled parts in standard option are shipped with 2,500 units per 13" or 33cm diameter reel. The reels are clear in color and is made of polystyrene plastic (anti-static coated).

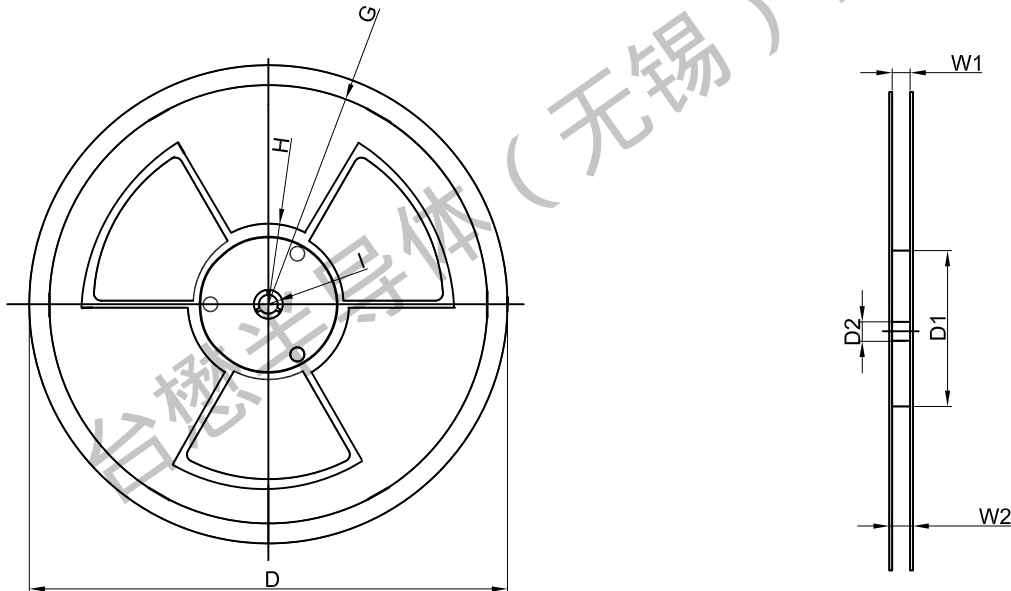
ALL DIM IN mm

Dimensions are in millimeter										
Pkg type	a	B	C	d	E	F	P0	P	P1	W
PDFN5x6-8L	6.40	5.40	2.10	Ø1.50	1.75	5.50	4.00	8.00	2.00	12.00

PDFN5x6-8L Tape Leader and Trailer



PDFN5x6-8L Reel



Dimensions are in millimeter								
Reel Option	D	D1	D2	G	H	I	W1	W2
13"Dia	Ø330.00	100.00	13.00	R135.00	R55.00	R6.50	12.00	14.00

REEL	Reel Size	Box	Box Size(mm)	Carton	Carton Size(mm)	G.W.(kg)
5,000 pcs	13 inch	10,000 pcs	370×355×52	50,000 pcs	400×360×368	



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Revision history:

Date	Rev	Description	Page
2023.05.24	23.05	Original	